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Dimensions	
Chip Size	3040
L	7.6mm +/-0.4mm
W	10.2mm +/-0.4mm
T	2.5mm +/-0.20mm
B	1.27mm +/-0.4mm

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	350

General Information	
Series	SMD Indust COG HVHT200C Pulse
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Pulse Discharge, Ultra-Stable, Low Loss
Features	High Temperature
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	870 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	0.01 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	10%
Voltage DC	2000 VDC
Dielectric Withstanding Voltage	3500 VDC
Temperature Range	-55/+200°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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